What is claimed is:

1. A molded product comprising a dielectric constant of 3.0 or less and a dielectric dissipation factor of 0.04 or less obtained by the injection molding of a wholly aromatic liquid crystal polyester resin composition which comprises 45 to 90 percent by weight of a wholly aromatic liquid crystal polyester having a melting point of 320°C or more, 10 to 40 percent by weight of an inorganic spherical hollow material having an aspect ratio of 2 or less, and 0 to 15 percent by weight (100 percent by weight as a total) of an inorganic filler having an aspect ratio of 4 or more.

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- 2. The molded product according to claim 1, wherein said wholly aromatic liquid crystal polyester is prepared by the polycondensation of 80 to 100 percent by mole of p-hydroxy benzoic acid (I), terephthalic acid (II), and 4,4'- dihydroxydiphenyl (III) (including the derivatives) (provided that a total of (I) and (II) is made more than 60 mole percent) and 0 to 20 percent by mole of other aromatic compound which can conduct a decondensation reaction with any one of (I), (II), or (III).
- 3. The molded product according to any of claims 1 to 3, wherein an apparent viscosity at a melting point +20°C of said wholly aromatic liquid crystal polyester is 5,000 poise or less.
- 4. The molded product according to any of claims 1 to 3, wherein the above mentioned inorganic spherical hollow material having an aspect ratio of 2 or less is an average particle diameter of 5 to $200\mu m$, and a rate of volume hollowness of 50 percent or more.
- 5. The molded product according to any of claims 1 to 4, wherein the inorganic filler having an aspect ratio of 4 or more is a glass fiber having an average diameter of $20\mu m$ or less and/or talc having an average particle diameter of $100\mu m$ or less and additionally the weight percent is in a range of 5 to 15.
- 6. The molded product according to any of claims 1 to 5, comprising a portion of a thickness 0.5mm or less and comprising a relative dielectric constant of said

portion 3 or less.

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7. The molded product according to any of claims 1 to 6, comprising a portable wireless telecommunications equipment having said molded product as a fixing or a holding member of a transmitting and receiving component.